



# 20V N-Channel MOSFET



#### **SOT-23**

# H

#### Pin Definition:

- 1. Gate
- 2. Source
- 3. Drain

#### **PRODUCT SUMMARY**

V <sub>DS</sub> (V)	$V_{DS}(V)$ $R_{DS(on)}(m\Omega)$	
20	33 @ V <sub>GS</sub> = 4.5V	4
	40 @ V <sub>GS</sub> = 2.5V	3.2
	100 @ V <sub>GS</sub> = 1.8V	2.0

#### **Features**

- Advance Trench Process Technology
- High Density Cell Design for Ultra Low On-resistance

#### **Application**

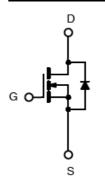
- Load Switch
- PA Switch

## **Ordering Information**

Part No.	Package	Packing
TSM2310CX RFG	SOT-23	3Kpcs / 7" Reel

Note: "G" denote for Green Product

#### **Block Diagram**



N-Channel MOSFET

## **Absolute Maximum Rating** (Ta = 25°C unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-Source Voltage		$V_{ t DS}$	20	V
Gate-Source Voltage		$V_{GS}$	±12	V
Continuous Drain Current, V <sub>GS</sub> @4.5V	,	I <sub>D</sub>	4	А
Pulsed Drain Current, V <sub>GS</sub> @4.5V		I <sub>DM</sub>	15	Α
Continuous Source Current (Diode Co	enduction) <sup>a,b</sup>	I <sub>S</sub>	1.0	Α
Masimus Bassa Binain atian	Ta = 25°C		1.25	
Maximum Power Dissipation	Ta = 75°C	P <sub>D</sub>	0.8	W
Operating Junction Temperature		T <sub>J</sub>	+150	°C
Operating Junction and Storage Temp	erature Range	T <sub>J</sub> , T <sub>STG</sub>	T <sub>J</sub> , T <sub>STG</sub> -55 to +150	

#### **Thermal Performance**

Parameter	Symbol	Limit	Unit
Junction to Case Thermal Resistance	R⊖ <sub>JC</sub>	75	°C/W
Junction to Ambient Thermal Resistance (PCB mounted)	R⊖ <sub>JA</sub>	160	°C/W

#### Notes:

- a. Pulse width limited by the Maximum junction temperature
- b. Surface Mounted on FR4 Board, t ≤ 5 sec.



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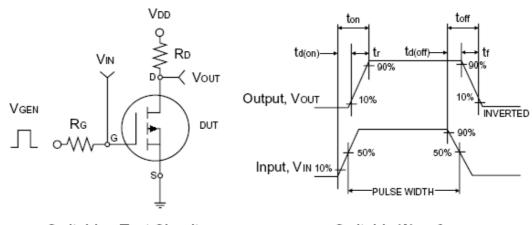


Electrical Specifications (Ta = 25°C unless otherwise noted)

Parameter	Conditions	Symbol	Min	Тур	Max	Unit
Static						
Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	BV <sub>DSS</sub>	20			V
Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	$V_{GS(TH)}$	0.6	0.8	1.2	V
Gate Body Leakage	$V_{GS} = \pm 4.5 V, V_{DS} = 0 V$	I <sub>GSS</sub>			±100	nA
Zero Gate Voltage Drain Current	$V_{DS} = 16V, V_{GS} = 0V$	I <sub>DSS</sub>			1.0	μΑ
On-State Drain Current	$V_{DS} \ge 10V, V_{GS} = 4.5V$	I <sub>D(ON)</sub>	15		-	Α
	$V_{GS} = 4.5V, I_D = 4A$			24	30	
Drain-Source On-State Resistance	$V_{GS} = 2.5V, I_D = 3.2A$	R <sub>DS(ON)</sub>		32	40	mΩ
	$V_{GS} = 1.8V, I_D = 2A$			80	100	
Forward Transconductance	$V_{DS} = 15V, I_{D} = 4A$	g <sub>fs</sub>		40		S
Diode Forward Voltage	$I_{S} = 1.6A, V_{GS} = 0V$	$V_{SD}$		0.8	1.2	V
Dynamic <sup>b</sup>						
Total Gate Charge	\/ 40\/ I 4A	$Q_{g}$		8.6		
Gate-Source Charge	$V_{DS} = 10V, I_D = 4A,$ $V_{GS} = 4.5V$	$Q_{gs}$		2		nC
Gate-Drain Charge	V <sub>GS</sub> = 4.5 V	$Q_{gd}$		2.7		
Input Capacitance	\/ 40\/ \/ 0\/	C <sub>iss</sub>		550		
Output Capacitance	$V_{DS} = 10V, V_{GS} = 0V,$	C <sub>oss</sub>		100	-	pF
Reverse Transfer Capacitance	f = 1.0MHz	$C_{rss}$		30		
Switching <sup>c</sup>						
Turn-On Delay Time	V 40V B 400	t <sub>d(on)</sub>		15		
Turn-On Rise Time	$V_{DD} = 10V, R_{L} = 10\Omega,$	t <sub>r</sub>		20		·- O
Turn-Off Delay Time	$I_D = 1A, V_{GEN} = 4.5V,$	t <sub>d(off)</sub>		40		nS
Turn-Off Fall Time	$R_G = 6\Omega$	t <sub>f</sub>		8		

#### Notes:

- a. pulse test: PW  $\leq 300 \mu S$ , duty cycle  $\leq 2\%$  b. For DESIGN AID ONLY, not subject to production testing.
- b. Switching time is essentially independent of operating temperature.



**Switching Test Circuit** 

Switchin Waveforms

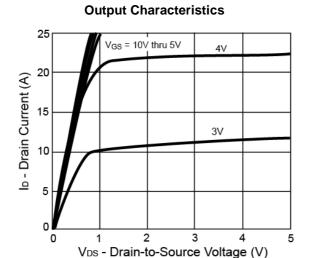


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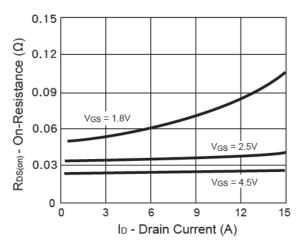
## 20V N-Channel MOSFET



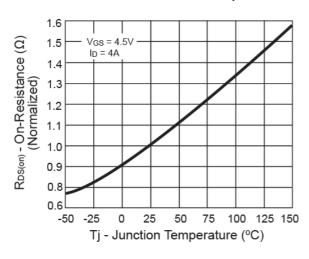
## Electrical Characteristics Curve (Ta = 25\o C, unless otherwise noted)



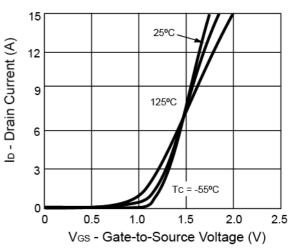
#### **On-Resistance vs. Drain Current**



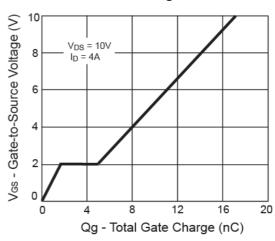
#### On-Resistance vs. Junction Temperature



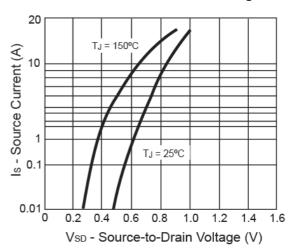
#### **Transfer Characteristics**



#### **Gate Charge**



#### Source-Drain Diode Forward Voltage





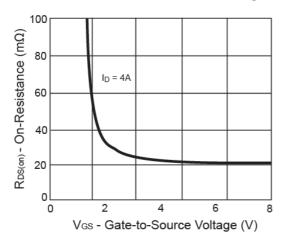
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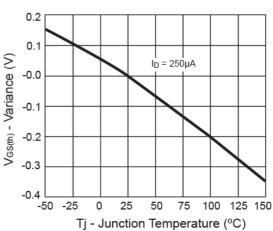


#### **Electrical Characteristics Curve** (Ta = 25°C, unless otherwise noted)

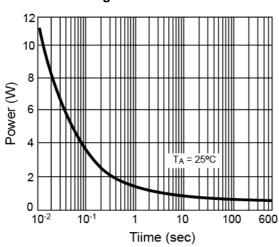
#### On-Resistance vs. Gate-Source Voltage



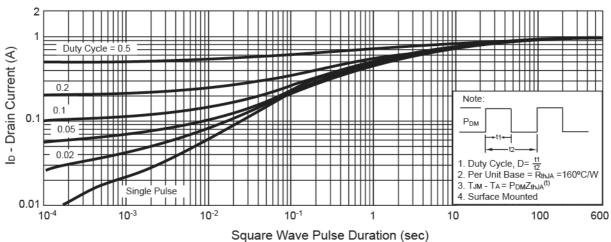
#### **Threshold Voltage**



#### Single Pulse Power



#### Normalized Thermal Transient Impedance, Junction-to-Ambient



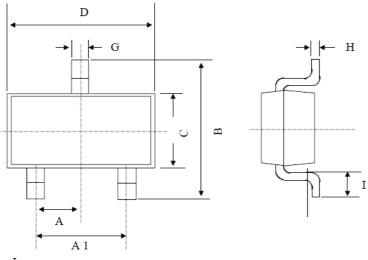




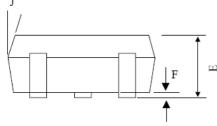


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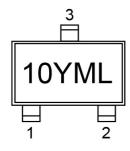
# **SOT-23 Mechanical Drawing**



	SOT-23 DIMENSION				
DIM	MILLIMETERS		INCHES		
	MIN	MAX	MIN	MAX.	
Α	0.95	BSC	0.037	BSC	
A1	1.9	BSC	0.074	BSC	
В	2.60	3.00	0.102	0.118	
С	1.40	1.70	0.055	0.067	
D	2.80	3.10	0.110	0.122	
Е	1.00	1.30	0.039	0.051	
F	0.00	0.10	0.000	0.004	
G	0.35	0.50	0.014	0.020	
Н	0.10	0.20	0.004	0.008	
I	0.30	0.60	0.012	0.024	
J	5°	10°	5°	10°	



# **Marking Diagram**



10 = Device Code

Y = Year Code

**M** = Month Code for Halogen Free Product

O =Jan P =Feb Q =Mar R =Apr

S =May T =Jun U =Jul V =Aug

W = Sep X = Oct Y = Nov Z = Dec

L = Lot Code



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